# Chemical content 74AUP1Z125GM

nexperia

| Type number | Package | Package description | Total product weight |
|---|---|---|---|
| 74AUP1Z125GM | SOT886 | XSON6 | 2.04718 mg |

| 12NC | Version | Pb-free soldering | | | Pb soldering | | | Number of processing cycles | Assembly site | RHF-indicator |
|---|---|---|---|---|---|---|---|---|---|---|
| | | MSL | PPT | MPPT | MSL | PPT | MPPT | | | |
| 935280525132 | 15 | 1 | 260 | 30 s | 1 | 240 | 20 s | 3 | Nijmegen, Netherlands; Bangkok, Thailand; Seremban, Malaysia | Pb D |
| 935280525115 | 13 | 1 | 260 | 30 s | 1 | 240 | 20 s | 3 | Bangkok, Thailand; Seremban, Malaysia; Nijmegen, Netherlands | Pb D |

| Subpart | Material group | Substances | CAS number | Mass(mg) | Mass(%) of subpart | Mass(%) of total product |
|---|---|---|---|---|---|---|
| Die | Doped Silicon | Silicon (Si) | 7440-21-3 | 0.09021 | 100.00000 | 4.40635 |
| | | subTotal | | 0.09021 | 100.00000 | 4.40635 |
| Component | Additive | Non hazardous | Proprietary | 0.00100 | 5.00000 | 0.04885 |
| | Filler | Aluminium Trioxide (Al2O3) | 1344-28-1 | 0.00800 | 40.00000 | 0.39078 |
| | Polymer | Bisphenol-A Bisphenol-A Diglycidyl Ether copolymer | 25036-25-3 | 0.00300 | 15.00000 | 0.14654 |
| | | Bisphenol-A/Epichlorohydrin Epoxy resin (generic) | 25068-38-6 | 0.00200 | 10.00000 | 0.09770 |
| | | Resin system | Proprietary | 0.00600 | 30.00000 | 0.29309 |
| | | subTotal | | 0.02000 | 100.00000 | 0.97696 |
| Lead Frame | Copper alloy | Copper (Cu) | 7440-50-8 | 1.01806 | 93.40000 | 49.72987 |
| | | Magnesium (Mg) | 7439-95-4 | 0.00164 | 0.15000 | 0.07987 |
| | | Nickel (Ni) - cas no. 7440-02-0 | 7440-02-0 | 0.03172 | 2.91000 | 1.54940 |
| | | Silicon (Si) | 7440-21-3 | 0.00687 | 0.63000 | 0.33544 |
| | Pure metal layer | Gold (Au) | 7440-57-5 | 0.00044 | 0.04000 | 0.02130 |
| | | Nickel (Ni) - cas no. 7440-02-0 | 7440-02-0 | 0.03008 | 2.76000 | 1.46953 |
| | | Palladium (Pd) | 7440-05-3 | 0.00120 | 0.11000 | 0.05857 |
| | | subTotal | | 1.09000 | 100.00000 | 53.24398 |
| Mould Compound | Filler | Silica -amorphous- | 7631-86-9 | 0.16000 | 20.00000 | 7.81563 |
| | | Silica fused | 60676-86-0 | 0.51600 | 64.50000 | 25.20540 |
| | Flame retardant | Metal hydroxide | Proprietary | 0.02400 | 3.00000 | 1.17234 |
| | Impurity | Silicon Dioxide (SiO2) | 14808-60-7 | 0.00400 | 0.50000 | 0.19539 |
| | Pigment | Carbon black | 1333-86-4 | 0.00240 | 0.30000 | 0.11723 |
| | Polymer | Phenol Formaldehyde resin (generic) | 9003-35-4 | 0.01760 | 2.20000 | 0.85972 |
| | | Phenolic resin | Proprietary | 0.02000 | 2.50000 | 0.97695 |
| | | Tetramethylbiphenyl diglycidyl ether | 85954-11-6 | 0.05600 | 7.00000 | 2.73547 |
| | | subTotal | | 0.80000 | 100.00000 | 39.07813 |
| Post-Plating | Impurity | Antimony (Sb) | 7440-36-0 | 0.00000 | 0.00300 | 0.00004 |
| | | Bismuth (Bi) | 7440-69-9 | 0.00000 | 0.00100 | 0.00001 |
| | | Copper (Cu) | 7440-50-8 | 0.00000 | 0.00100 | 0.00001 |
| | | Lead (Pb) | 7439-92-1 | 0.00000 | 0.00500 | 0.00007 |
| | Tin solder | Tin (Sn) | 7440-31-5 | 0.03000 | 99.99000 | 1.46528 |

| Subpart | Material group | Substances | CAS number | Mass(mg) | Mass(%) of subpart | Mass(%) of total product |
| --- | --- | --- | --- | --- | --- | --- |
| | | subTotal | | 0.03000 | 100.00000 | 1.46541 |
| Wire | Gold alloy | Gold (Au) | 7440-57-5 | 0.01681 | 99.00000 | 0.82090 |
| | | Palladium (Pd) | 7440-05-3 | 0.00017 | 1.00000 | 0.00829 |
| | | subTotal | | 0.01698 | 100.00000 | 0.82919 |

## Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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